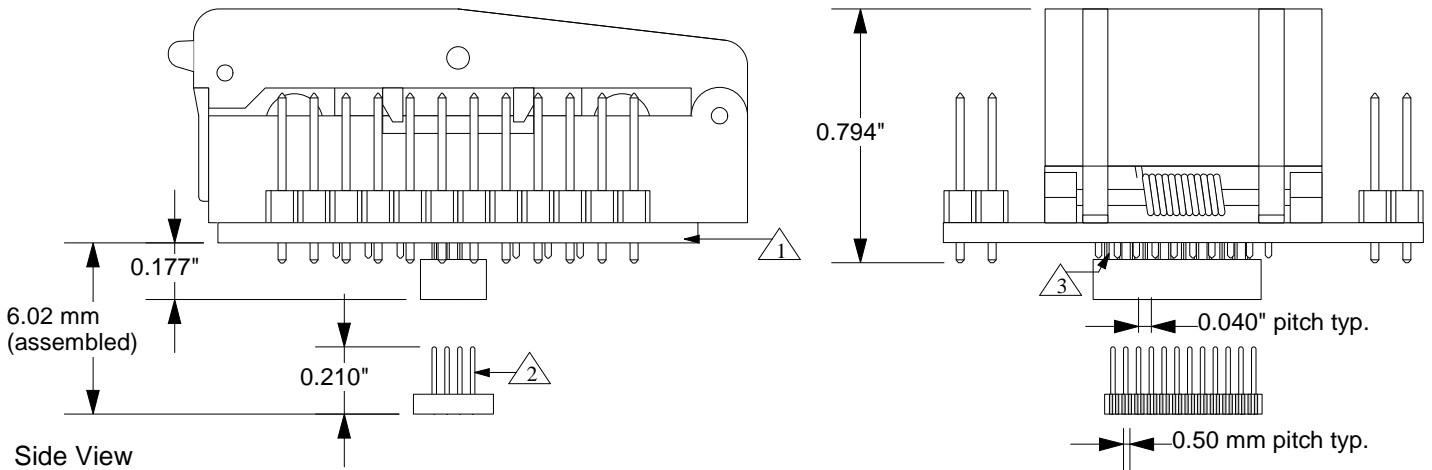


Top View



Side View

1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating

2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10μ" Au over 50μ" Ni (min.).


3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10μ" Au over 50μ" Ni (min.). Contact material- BeCu; finish 10μ" Au over 100μ" Ni (min.)

4 Test points: material- Phosphor Bronze; plating- Sn over 50μ" Ni. Gold flash on contact end.

Description: Carrier Adaptor

48 position TSSOP (II) ZIF socket with mini grid array pluggable interface to leadless surface mount foot.

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

	© 1999 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Status: Released	Scale 2:1	Rev: A
		Drawing: E Smolentseva		Date: 02/16/99
		File: CA-SO48C-Z-L-T-01 Dwg		Modified: